

L Number	Hits	Search Text	DB	Time stamp
117	36	361/278.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:28
118	37	361/329.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:33
119	0		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:25
120	37	(361/329.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)) not (361/278.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:25
121	125	361/278.ccls. and (@ad<19980407)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:28
122	8	361/292.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:34
123	10608	361/\$.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:59
124	0		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 20:34
125	1846	(361/\$.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)) and ((pore or porous or hole or void or voids) with (electrode or terminal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:36
126	191	(361/\$.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)) and ((pore or porous or hole or void or voids) near (electrode or terminal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 20:10
127	74	361/303.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 20:15
128	13	361/324.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 20:09
129	35444	257/\$.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 20:09
130	5906	(257/\$.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)) and ((ceramic near (chip or die)) or capacitor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 20:10

131	78	((257/\$.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)) and ((ceramic near (chip or die)) or capacitor)) and ((pore or porous or hole or void or voids) near (electrode or terminal)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:11
132	22	361/308.1.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:21
133	0	361/315.1.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:27
134	43	361/314.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:33
135	56	361/321.1.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:33
136	0	361/329.1.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:37
137	37	361/329.ccls. and (@ad<19980407) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:33
138	1152	((ceramic NEAR (CHIP OR DIE)) and ((pore or porous or hole or void or voids)(baking same (electrode or terminal))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:37
139	744	((ceramic NEAR (CHIP OR DIE)) and ((pore or porous or hole or void or voids)(baking same (electrode or terminal)))) and (@ad<19980407)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:41
140	57685	((ceramic NEAR (CHIP OR DIE)) OR Capacitor) and ((pore or porous or hole or void or voids)(baking same (electrode or terminal)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:38
141	368	((ceramic NEAR (CHIP OR DIE)) OR Capacitor) and ((pore or porous or hole or void or voids)and baking) same (electrode or terminal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:41
142	477	((ceramic NEAR (CHIP OR DIE)) OR Capacitor) and ((pore or porous or hole or void or voids)and baking) same (electrode or terminal OR PASTE))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:41
143	179	((ceramic NEAR (CHIP OR DIE)) OR Capacitor) and ((pore or porous or hole or void or voids)and baking) same (electrode or terminal OR PASTE))) and (@ad<19980407)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/27 20:41
-	4	((wiring or trace) near (wide and narrow)) and (substrate with (chip or die))	USPAT	2004/07/27 13:32
-	1	("20020060369").PN.	US-PGPUB	2004/07/27 16:49

-	360	((capacitor and (chip or die)) near ceramic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 17:06
-	224	((capacitor and (chip or die)) near ceramic)) and (@ad<19980407)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 17:06
-	62	((capacitor and (chip or die)) near ceramic)) and (@ad<19980407)) and (pore or porous or hole or void or voids)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/27 19:17